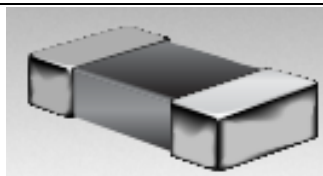


MATERIAL DECLARATION SHEET



Material Number	CVH160808 SERIES		
Product Line	Multilayer Chip Bead		
Compliance Date	2020.08.28		
RoHS Compliant	Y	MSL	1



No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic body	Ferrite Powder	0.0033736	Iron oxide	1309-37-1	68%	52.40%	77.2%
				Copper oxide	1317-38-0	8%	6.20%	
				Nickel oxide	7440-02-0	5%	3.90%	
				Zinc oxide	1314-13-2	19%	14.70%	
2	Ceramic body	Silver Conductor	0.000437	Silver	7440-22-4	100%	10.00%	10.00%
3	Ceramic body	Internal Electrode	0.0003059	Silver	7440-22-4	100%	7.00%	7.00%
4	Termination	Plating	0.00006118	Nickel	7440-02-0	100%	1.40%	1.40%
5	External electrode	Solder	0.00019228	Tin	7440-31-5	100%	4.40%	4.40%
Total weight			0.00437					

This Document was updated on: 2020.08.28

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.